

Product	Application Notes	Cure Type	Rheology	Viscosity mPas	Hardness Shore A	UL94 V-0	Colour	Tensile Strength N/mm <sup>2</sup>	Elongation %	Temperature Range	Cure Time	Volume Resistivity ohm.cm	Dielectric Strength KV/mm	Thermal Conductivity W/mk
<b>1 Part Silicones</b>														
Elastosil N9111 Black	Very popular neutral cure, non-corrosive adhesive/sealant, with excellent primerless adhesion. Shear-thinning, non slump paste. Medium hardness. Also suitable for CIPG and FIPG gasket applications. UL94 V-0. Electronic component staking, ruggedising, wire tacking, Automotive, Appliances.	Alkoxy	Non slump paste, thixotropic	800,000	30	Yes	Black	2.2	500	-45 to 180°C	Skin 25-30 mins 12h/mm	10 <sup>14</sup>	21	0.2
Elastosil N9111 White	Compatible with all silicone potting compounds; suitable for use in dam and fill applications.						White							
Elastosil N2034	Flowable, non-corrosive black silicone for technical applications including bonding, sealing, coating, potting and gasketing. Self-levelling with medium hardness when cured, and flame retardant.	Alkoxy	Self levelling	25,000	35	Yes	Black	2.0	200	-50 to 180°C	Skin 20 mins			0.2
Elastosil N2189	Non-corrosive, neutral cure, hard but flexible silicone. Mineral oil and coolant resistant, with good heat stability and flame retardancy. A particularly good choice in applications such as automotive gasketing. UL94 V-0.	Alkoxy	Non slump		45	Yes	Black	2.5	250	up to 180°C	Skin 15 mins			0.25
Elastosil N2199	Highly flexible, translucent silicone which meets the criteria of MIL-SPEC 46146. Neutral cure and good adhesion to many substrates including plastics, glass, metals and ceramic. Cured product has outstanding resistance to weathering, ageing, moisture, and UV light.	Alkoxy	Non slump		30		Translucent	2.5	350	-45 to 180°C	Skin 15 mins			0.2
Elastosil E4	Soft, non-slump transparent adhesive sealant with low hardness, useful for signage, CIP gasketing and sealing applications. Highly elastic with excellent recovery after compression.	Acetoxy	Non slump		15		Transparent	2.0	750	up to 180°C	Skin 20-25 mins 12h/mm	10 <sup>14</sup>	21	0.2
Elastosil E10	Flowable sealant with excellent heat stability up to 250°C, long-term elasticity under thermal stress, and good mechanical properties. Low hardness. Applications include sealing of heating elements.	Acetoxy	Very low viscosity	8,000	25		Red	2.5	300	up to 250°C	Skin 10-15 mins 12h/mm	10 <sup>14</sup>	21	0.2
Elastosil E14 Red	Non-sag sealant with a broad adhesion profile and excellent heat stability up to 250°C. Medium hardness. Applications include small appliances, FIP gaskets, and HVAC.	Acetoxy	Non slump paste	1,000,000	32		Red	2.5	400	up to 250°C	Skin 15-20 mins 12h/mm			0.2
Elastosil E41	Transparent sealant with excellent adhesion to cured silicone.	Acetoxy	Self levelling	100,000	40		Transparent	6.0	350	up to 200°C	Skin 15 mins			0.2
Elastosil E43 N	Food compliant, high viscosity, fast curing adhesive sealant which cures to a transparent, medium-hard elastomer. High elasticity, tensile strength and tear resistance. Adheres to cured silicone rubber. Temperature resistance up to 200°C.	Acetoxy	Self levelling	300,000	30		Transparent	6.2	600	-50 to 180°C	Skin 5-10 mins 12h/mm			
Elastosil E50N	Food compliant, transparent silicone for coating and potting applications including textile coatings. Medium hardness, more rigid than E43N.	Acetoxy	Flowable	50,000	35		Transparent	1.5	150	up to 180°C	Skin 8-20 mins 12h/mm			0.2
Silpuran 4200	Medical-grade, biocompatible acetoxy-curing adhesive sealant which meets the requirements of ISO 10993 and USP Class VI. Fast skin time; medium hardness.	Condensation	Non slump	300,000	35		Translucent	5.5	300		Skin 5-10 minutes 12h/mm			
Semicosil 987	Rapid heat-curing black adhesive sealant for electronics applications, including CIP and FIP gaskets. High hardness.	Thermal	Non slump, thixotropic	350,000	50		Black	5.0	200	-50 to 180°C	6h at 100°C 1h at 130°C 10 mins at 150°C			0.2
Semicosil 989/1K	General purpose transparent adhesive for the electronics industry. FIPG and CIPG applications. Primerless adhesion to many substrates.	Thermal	Non slump, thixotropic	300,000	55		Transparent	5.0	200		6 h /100°C 10 mins /150°C	10 <sup>14</sup>	23	0.2

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Product	Application Notes	Cure Type	Mix Ratio	Viscosity mPas	Hardness Shore A	Colour	Tensile Strength N/mm <sup>2</sup>	Elongation %	Temperature Range	Pot Life	Cure Time	Volume Resistivity ohm.cm	Dielectric Strength KV/mm	Thermal Conductivity W/mk
<b>2 Part Silicones</b>														
Elastosil RT 601	Highly transparent, low viscosity electronics potting compound for circuit protection. Medium cured hardness. Also useful for optical applications (e.g. solar panels). Food compliant.	Addition	9:1	3,500	45	Transparent	6.0	100	150°C	90 mins	23°C/24 h 70°C/20 mins 100°C/10 mins	10 <sup>15</sup>	23	0.2
Elastosil RT 602	Low viscosity silicone potting compound with rapid heat cure, medium cured hardness and excellent heat stability. Food compliant.	Addition	9:1	3,500	30	Light grey	1.5	130	200°C	80 mins	23°C/24 h 70°C/20 mins 100°C/10 mins 150°C/5 mins	10 <sup>15</sup>		0.2
Elastosil RT 604	Softer than RT 601. Highly transparent, very low viscosity electronics potting compound for circuit protection. Also useful for optical applications (e.g. solar panels). Food compliant.	Addition	9:1	800	25	Transparent	1.0	100	150°C	90 mins	23°C/24 h 70°C/30 mins 100°C/8 mins 150°C/5 mins	10 <sup>15</sup>	23	0.2
Elastosil RT 607	Very hard, flame retardant silicone potting compound with rapid heat cure and excellent heat resistance. Food compliant.	Addition	9:1	10,000	55	Reddish-brown	3.5	100	210°C	80 mins	23°C/24 h 100°C/10 mins 150°C/5 mins	10 <sup>15</sup>	23	0.4
Elastosil RT 745	Tough gel with primerless adhesion and rapid heat cure. Applications include potting and encapsulation of components for measurement and control, sensor technology, and electronics including automotive.	Addition	1:1	1,000	15	Tranlucent-brownish			160°C	<240 mins	80°C/60 mins 120°C/10 mins 150°C/5 mins	10 <sup>16</sup>		0.2
Elastosil RT 745 S	Softer version of Elastosil RT 745. May be suitable for some automotive applications involving water immersion.	Addition	1:1	1,000	Shore 00 - 37	Translucent-brownish			160°C	<240 mins	80°C/60 mins 120°C/10 mins 150°C/5 mins	10 <sup>15</sup>		0.2
SilGel 612	Crystal clear silicone gel well suited to encapsulation of LEDs, manufacturing of solar panels, and electronics applications. Very low bleed, good adhesion, low stress, flame retardant. Rapid heat cure.	Addition	1:1	1,000	Very soft gel	Transparent			160°C	150 mins	23°C/8 h 100°C/15 mins 150°C/5 mins	10 <sup>15</sup>	23	0.2
SilGel 613	Similar to SilGel 612, but is lower viscosity and works with catalysts to speed up curing, including a UV-curing catalyst.	Addition	10:1	150	Very soft gel	Transparent			160°C	Varies with catalyst	Varies with catalyst			0.2
Elastosil RT K	Silicone potting compound, condensation curing with Cat T catalyst. Flowable, with good post mix self deaeration. Medium hardness.	Condensation	100:4	7,000	45	Light grey	2.0	130	-50°C to 180°C	150 mins	23°C/3 - 7 h depending on mix ratio	10 <sup>14</sup>	23	0.3
Elastosil RT 426	Potting and encapsulation compound for electronics and lighting applications, with excellent heat resistance and high hardness.	Condensation		15,000	60	Reddish-Brown	4.5	120	200°C	Varies with catalyst	Varies with catalyst			0.4
Elastosil RT 428	Thermally conductive potting compound with excellent heat resistance and high hardness. Recommended for electronics encapsulation.	Condensation	100:3	12,000	65	Reddish-brown	6.0	90	200°C	50 mins	23°C/8 h			0.3
Semicosil 961 TC	Gap filler which cures to a soft, tacky rubber. Highly thermally conductive interface material for electronic heat sink applications.	Addition	1:1	130,000	25	Yellow			-50° to 130°C	60 mins	23°C/5 h 100°C/5 mins	10 <sup>13</sup>	8	2.3

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